Bench test of the ATLASPix3 at IHEP

Silicon Tracker working group

Outline

Background and Introduction to ATLASPix3

Activities going on @IHEP

Summary and outlook

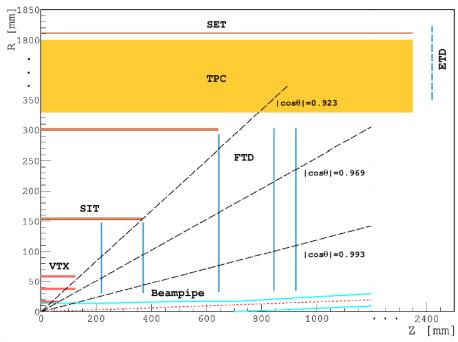
Backgrounds

> CEPC Baseline tracker

- Mixed Tracker (TPC + Silicon)
 - 3 layers, 5 disks of silicon sensors
 - Large area (50 m² if built in pixels) to be covered
- Limited R&D time
- Comparable requirements with ATLAS/ALICE
 - Bunch spacing, material budget, spatial resolution ...
 - Plenty of experience to learn from

> ATLASPix/ATLASPix3

- A CMOS sensor developed to fulfill the requirement for the ATLAS ITK outer layer upgrade
- Functional sensor available for prototyping Optimization for CEPC Tracker

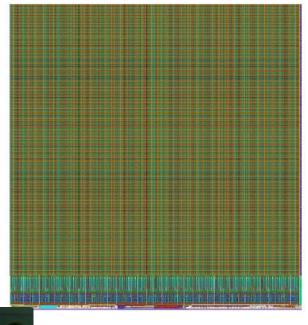


Introduction to ATLASPix3

ATLASPix3

- HV-CMOS Monolithic chip
- Chip Size: 2.02 cm by 2.1 cm (Full reticule size)
- TSI 180 nm HV process on 200 Ω cm substrate
- 132 cols each contains 372 pixels(50 μm x 150 μm)
- Each Pixel:
 - Charge sensitive Amplifier
 - Comparator with threshold tune DAC
 - 4 bit RAM
- 1.25 GBit/s downlink
- Chips(18+1) arrived @IHEP ~ a month ago







Introduction: Test setup

Lab Measurement setup (developed by KIT)

Artrix-7 FPGA board

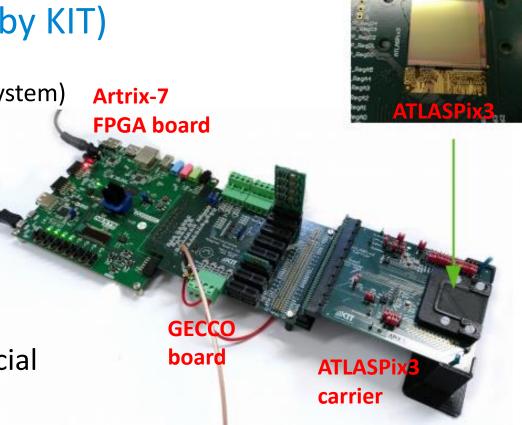
GECCO board(GEneric Configuration and COntrol system)

PCle connector (with DUT)

Highly modular with function cards(versatile)

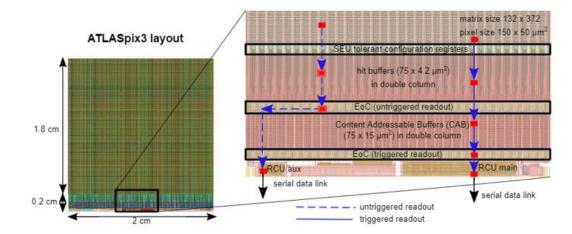
- Easy changing of DUT sample (no cabling)
- 90° Adapter
- ATLASPix3 Carrier PCB
- Firmware
- Software(Qt based)

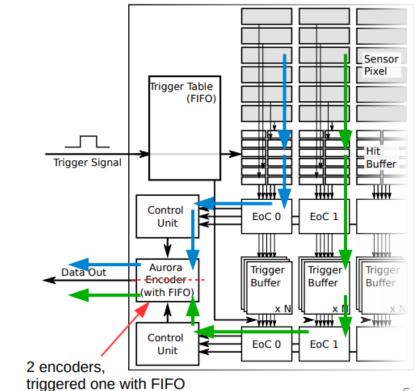
ATLASPix3 Telescope setup (feasible using special structure)



Introduction: Readout

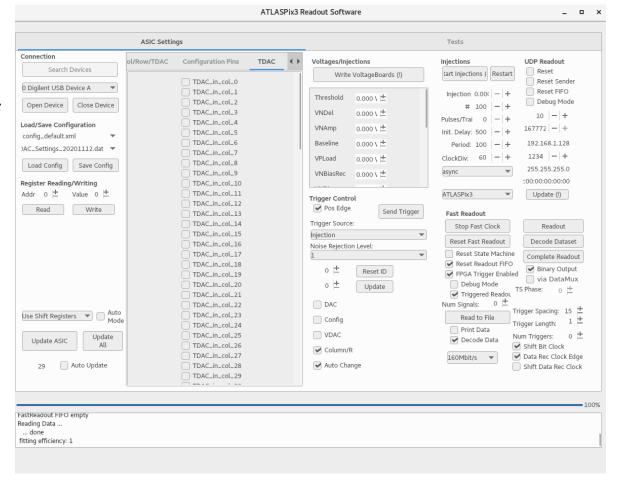
- ➤ Digital Part(10% total area):
 - configuration registers
 - hit buffer for each pixel
 - Untriggered and triggered End of Column(EoCs)
 - Content addressable buffer(CAB)
 - Readout Control Unit(RCU main and auxiliary)
- ➤ Hit information from one pixel transmitted to the hit buffer through long routing metal lines
- ➤ HitBuffer stores the global time stamp(TS) and generate a hit word(32 bit)
- > Triggered and Triggerless readout
 - ➤ Triggered: transferred to CAB where the hits are filtered based on a trigger signal
 - ➤ Triggerless: transferred to EOC for untriggered readout



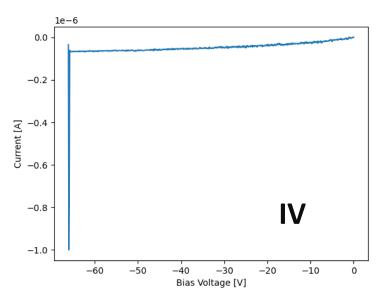


Introduction: DAQ software

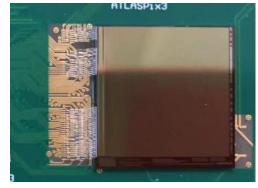
- Powerful DAQ software (KIT)
 - Using on ATLASPix3 testing since the end of 2019
 - Based on C++ with Qt framework
 - Graphical User Interface
 - Managing the Configurations for DUT and Firmware
 - Very helpful for system debugging
- It works

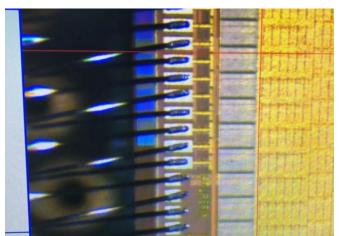


- Test system @IHEP (Tremendous help from Rudolf)
- Wired Bonded in IHEP clean room
 - 5 out of 6 bonded chips work
- Basic IV and analog output
 - Low leakage current of < 70 nA @ -60V



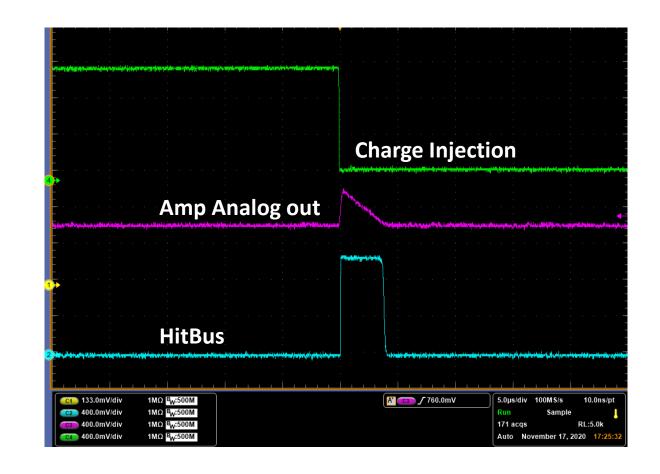






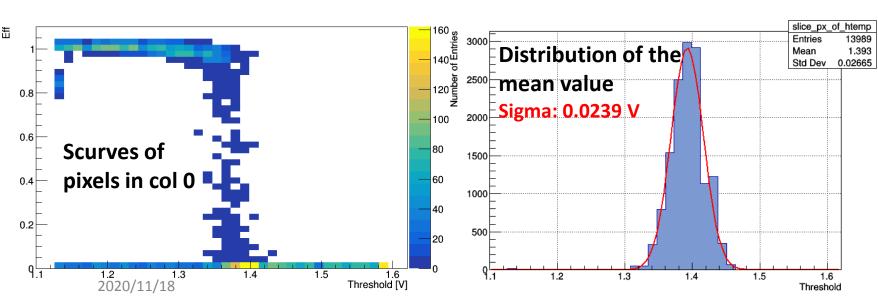


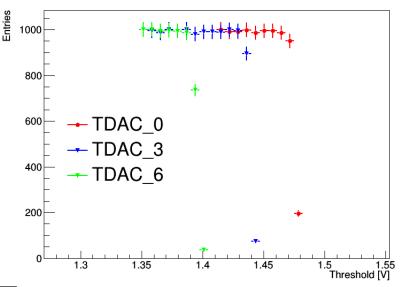
- Test system @IHEP
- Wired Bonded in IHEP clean room
 - 5 out of 6 bonded chips working
- Basic IV and <u>analog output</u>
- Decoding processes understood

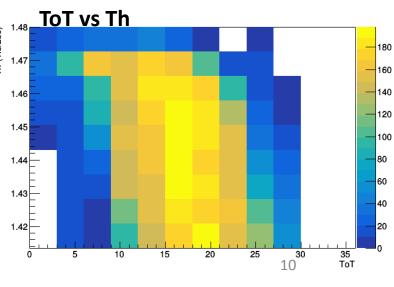


Tests with Triggered readout @IHEP

- Scurve for large area of pixels
 - Distribution of mean value (sigma: 0.0239 V)
- ToT vs Threshold
- Threshold scan (varies TDAC): Trimming to be done





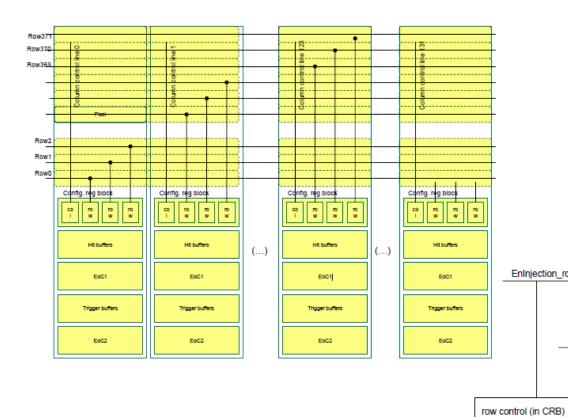


Summary and Outlook

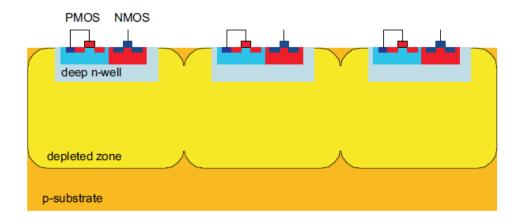
- > ATLASPix3 chips arrived at IHEP last month
 - ✓ Wire bonding, Test setup, software
 - ✓ IV curve, Analog signal
 - □ Digital readout, SCurve, Trimming, ToTCalibration to be done very soon
- > Chips and System work, configurations to be further fine tuned
- > (future) Pixel sensor design optimization toward the CEPC tracker
 - ➤ QuardModule for the demonstrator being prepared @Milano
 - \triangleright Sensor design (smaller pixel size 25 \times 160 μ m²) for CEPC under preparation
 - ➤ Switch to Chinese foundry (under discussion)

Backup: ATLASPix3

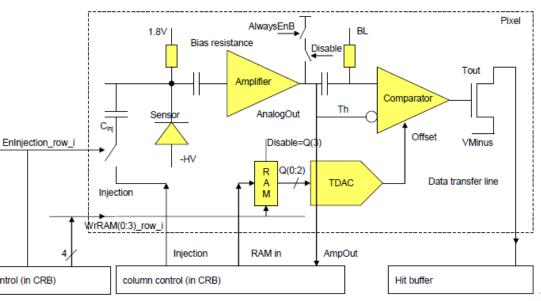
Block scheme of the pixel matrix and column circuits



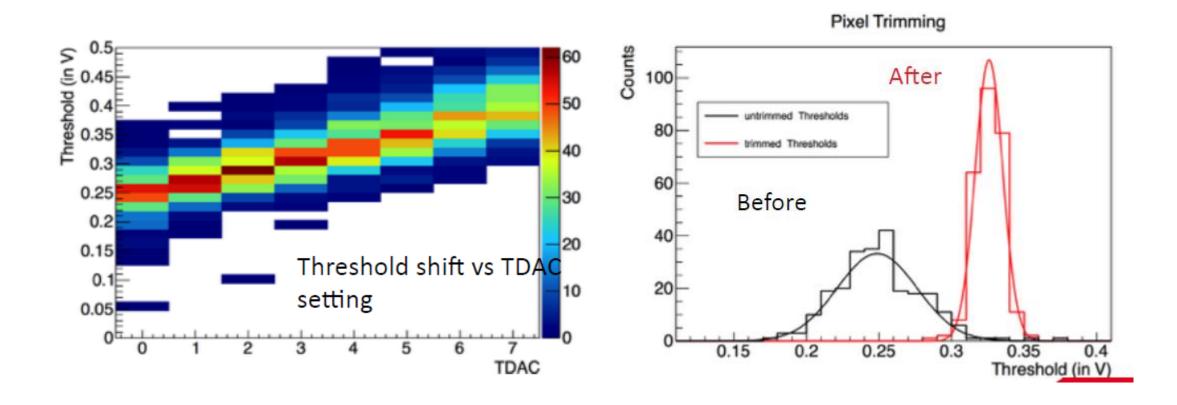
HV-CMOS structure



Pixel Schematics

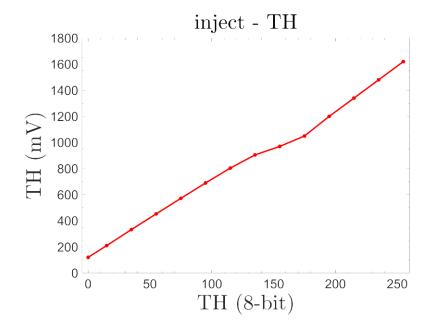


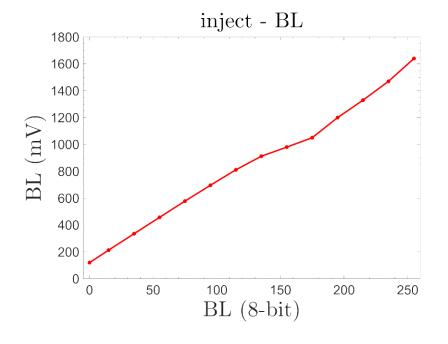
backup



DAC linearity characterization (Milano)

- Threshold, Baseline, Injection pulse
- Ampout, ToT





14